

# EA5070JA12-27.000M



## ITEM DESCRIPTION

Quartz Crystal Resonator 5.0mm x 7.0mm x 1.3mm 4 Pad Ceramic Surface Mount (SMD) 27.000MHz  $\pm 15$ ppm at 25°C,  $\pm 30$ ppm over -40°C to +85°C 12pF Parallel Resonant

## ELECTRICAL SPECIFICATIONS

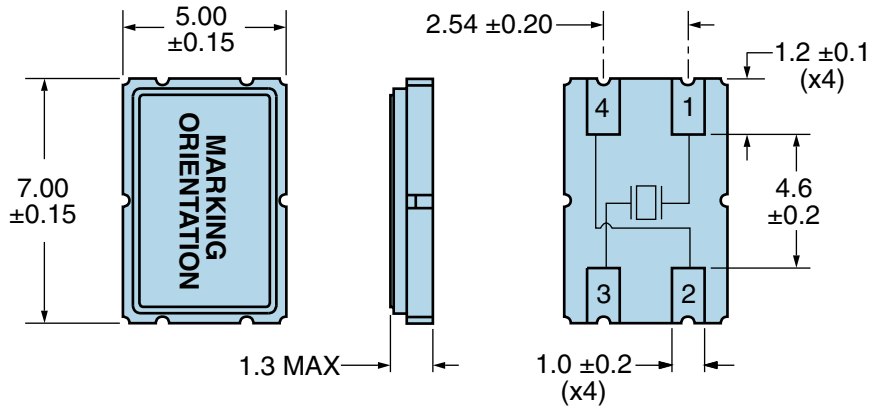
Nominal Frequency	27.000MHz
Frequency Tolerance/Stability	$\pm 15$ ppm at 25°C, $\pm 30$ ppm over -40°C to +85°C
Aging at 25°C	$\pm 3$ ppm/year Maximum
Load Capacitance	12pF Parallel Resonant
Shunt Capacitance	7pF Maximum
Equivalent Series Resistance	30 Ohms Maximum
Mode of Operation	AT-Cut Fundamental
Drive Level	50 $\mu$ Watts Maximum
Spurious Response	-3dB Minimum (Measured from Fo to Fo +5000ppm)
Storage Temperature Range	-40°C to +85°C
Insulation Resistance	500 Megaohms Minimum (Measured at 100Vdc)

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Flammability	UL94-V0
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A

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## MECHANICAL DIMENSIONS (all dimensions in millimeters)



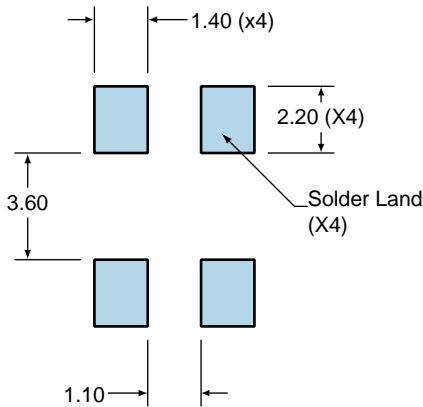
Note: Chamfer and index mark not shown.

PIN	CONNECTION
1	Crystal
2	Cover/Ground
3	Crystal
4	Cover/Ground

LINE	MARKING
1	<b>E27.00</b> E=Ecliptek Designator
2	<b>XXXXX</b> XXXXX=Ecliptek Manufacturing Identifier

## Suggested Solder Pad Layout

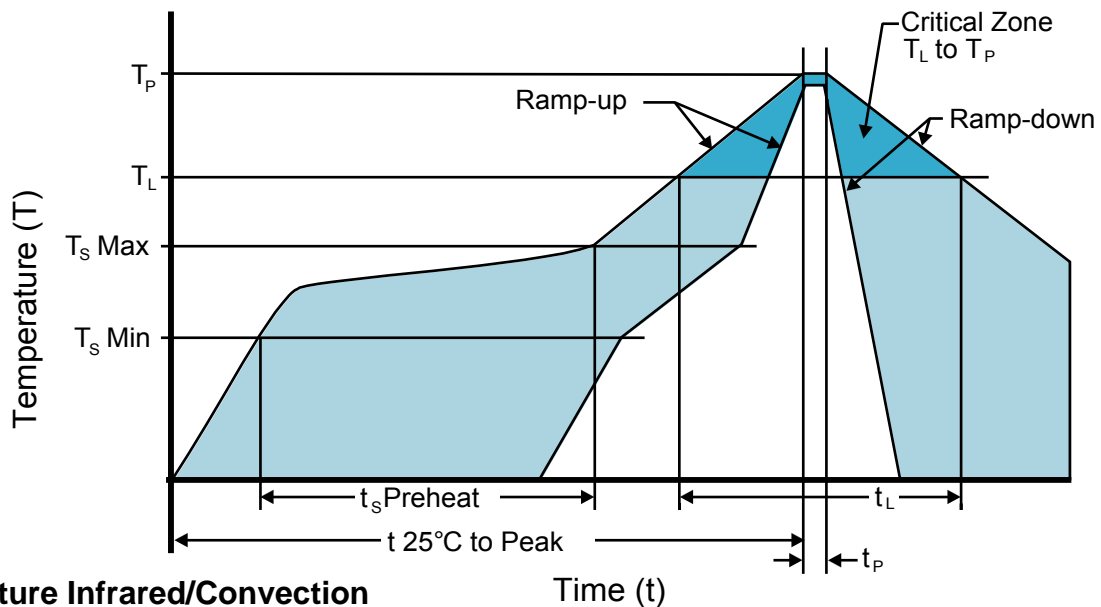
All Dimensions in Millimeters



All Tolerances are ±0.1

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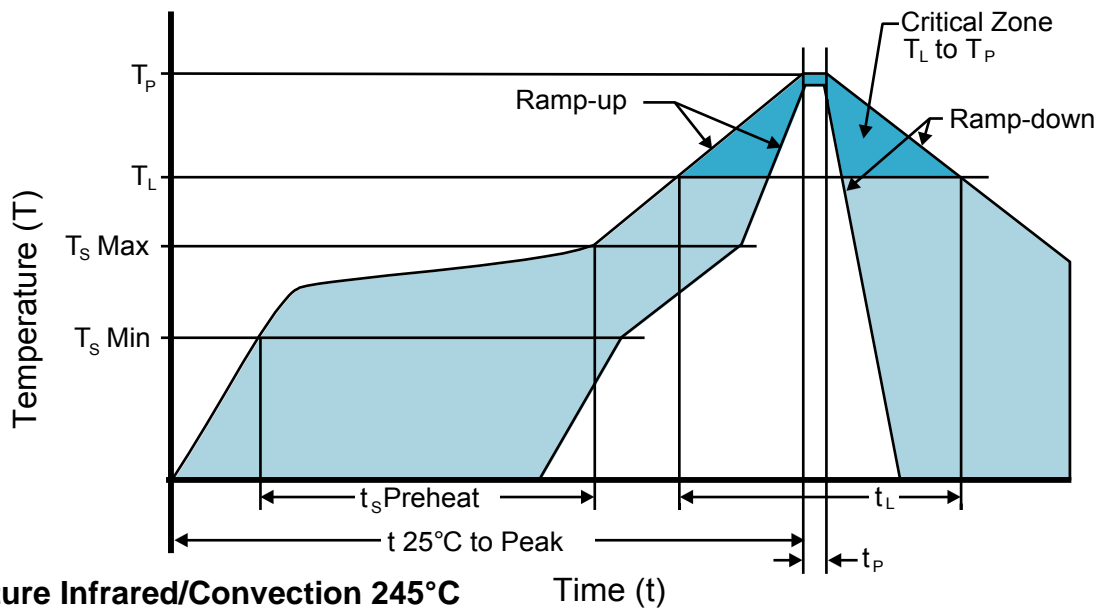
## Recommended Solder Reflow Methods

**High Temperature Infrared/Convection**

<b><math>T_s</math> MAX to <math>T_L</math> (Ramp-up Rate)</b>	3°C/Second Maximum
<b>Preheat</b>	
- Temperature Minimum ( $T_s$ MIN)	150°C
- Temperature Typical ( $T_s$ TYP)	175°C
- Temperature Maximum ( $T_s$ MAX)	200°C
- Time ( $t_s$ MIN)	60 - 180 Seconds
<b>Ramp-up Rate (<math>T_L</math> to <math>T_P</math>)</b>	3°C/Second Maximum
<b>Time Maintained Above:</b>	
- Temperature ( $T_L$ )	217°C
- Time ( $t_L$ )	60 - 150 Seconds
<b>Peak Temperature (<math>T_P</math>)</b>	260°C Maximum for 10 Seconds Maximum
<b>Target Peak Temperature (<math>T_P</math> Target)</b>	250°C +0/-5°C
<b>Time within 5°C of actual peak (<math>t_p</math>)</b>	20 - 40 Seconds
<b>Ramp-down Rate</b>	6°C/Second Maximum
<b>Time 25°C to Peak Temperature (t)</b>	8 Minutes Maximum
<b>Moisture Sensitivity Level</b>	Level 1
<b>Additional Notes</b>	Temperatures shown are applied to body of device.

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## Recommended Solder Reflow Methods

**Low Temperature Infrared/Convection 245°C**

<b><math>T_S</math> MAX to <math>T_L</math> (Ramp-up Rate)</b>	5°C/Second Maximum
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**Preheat**

- Temperature Minimum ( $T_S$ MIN)	N/A
- Temperature Typical ( $T_S$ TYP)	150°C
- Temperature Maximum ( $T_S$ MAX)	N/A
- Time ( $t_s$ MIN)	30 - 60 Seconds

<b>Ramp-up Rate (<math>T_L</math> to <math>T_P</math>)</b>	5°C/Second Maximum
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**Time Maintained Above:**

- Temperature ( $T_L$ )	150°C
- Time ( $t_L$ )	200 Seconds Maximum

<b>Peak Temperature (<math>T_P</math>)</b>	245°C Maximum
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<b>Target Peak Temperature (<math>T_P</math> Target)</b>	245°C Maximum 2 Times / 230°C Maximum 1 Time
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<b>Time within 5°C of actual peak (<math>t_p</math>)</b>	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time
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<b>Ramp-down Rate</b>	5°C/Second Maximum
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<b>Time 25°C to Peak Temperature (t)</b>	N/A
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<b>Moisture Sensitivity Level</b>	Level 1
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<b>Additional Notes</b>	Temperatures shown are applied to body of device.
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**Low Temperature Manual Soldering**

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

**High Temperature Manual Soldering**

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)